

Quarterly Reliability Monitoring Results

Quarters: Q1/2023 to Q4/2024

Based on structural similarity

Supplier		User Part Number				
Nexperia B.V.		BAS40H				
Name of Laboratory		Part Description				
Assembly reliability labs		Nexperia DHAM Schottky SMD package				
Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects
# 1	<b>TEST</b> Pre- and Post-Stress Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below
# 2	<b>PC</b> Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	1602	61540	0
# 5	<b>HTRB</b> High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage <sup>[1]</sup>	1000 hours	231	9240	0
# 7	<b>TC</b> Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	500 cycles	337	13480	0
# 8 or	<b>UHAST</b> Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	96 hours	337	13480	0
# 8a	<b>AC</b> Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)				
# 9	<b>H3TRB</b> High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage <sup>[1], [2]</sup>	1000 hours	337	13480	0
# 10	<b>IOL</b> Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C	333 hours	337	13480	0
# 20	<b>RSH</b> Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	254	7620	0
# 21	<b>SD</b> Solderability	J-STD-002		210	6300	0

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	9240	0	0,46	2,18E+09